

Document	Datasheet
Type	Multilayer Chip Antenna
Application	2.4GHz
Part No.	ALA321C3
Revision	7.0

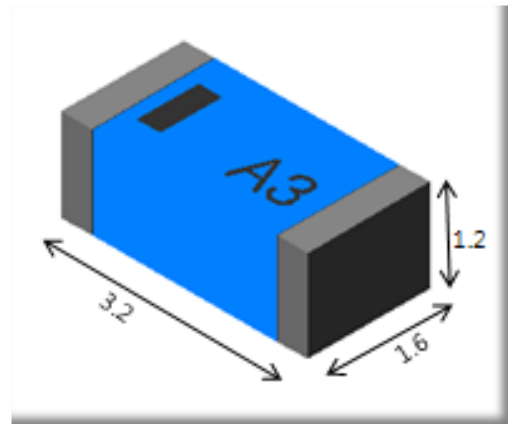
# DATASHEET

## Application

Bluetooth  
Zigbee  
WLAN (IEEE 802.11 b/g)  
ISM 2.4GHz Wireless Devices

## Features

Helical Structure  
Small Size (3.2\*1.6\*1.2mm<sup>3</sup>)  
Easy Optimizing  
    with external lumped matching components  
SMT Available under Pb-free Condition  
RoHS Compliant



# AMOTECH

### Notes

*The contents of this datasheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.*

## Revision History

Rev. No	Date	Title	Contents	Page
7	'09.04.07	Format	Changed document format	

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## 1. Specifications

### 1.1 Electrical Specifications

No	Item	Spec.	Remark
1	Frequency Range [GHz]	2.4 ~2.485	
2	VSWR	Max 3.0:1	
3	Peak Gain [dBi]	typ. 2.3	
4	Total Avg. Gain [dBi]	typ. -0.6	
5	Efficiency [%]	typ. 84	
6	Polarization	Linear	
7	Impedance [ $\Omega$ ]	Nominal 50	

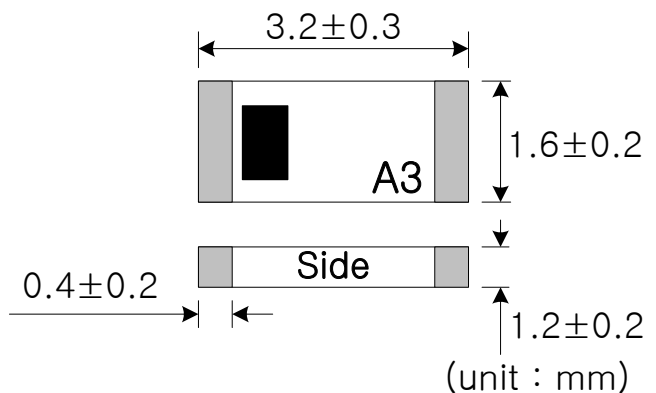
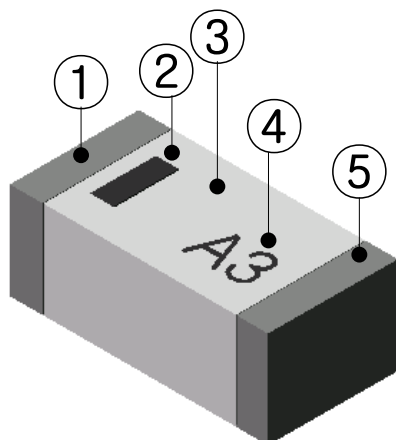
- ✓ The results are measured on the 10x43mm<sup>2</sup> evaluation board(EVB).
- ✓ See Page 6. for more detail gain parameter

### 1.2 Mechanical Specifications

No	Item	Spec.	Remark
1	Dimensions (LxWxH)	3.2x1.6x1.2 mm <sup>3</sup>	
2	Unit Weight	typ. 20 mg	
3	Operating Temperature	-35 ~ +85 °C	

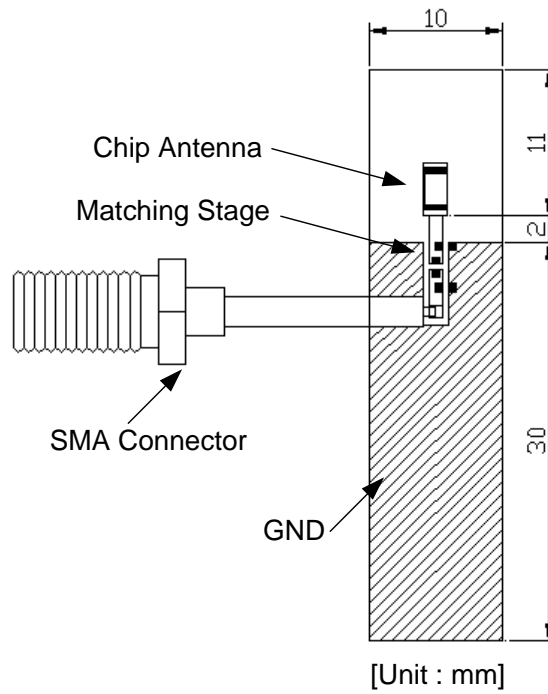
### 1.3 Appearance & Material

No	Item	Function	Material
①	External Electrode	Soldering, Input Port	Ag/Ni/Sn
②	Direction index	Indication of	Ceramic
③	Ceramic Body	-	Ceramic
④	Model No. index	-	Ceramic
⑤	External Electrode	Soldering	Ag/Ni/Sn



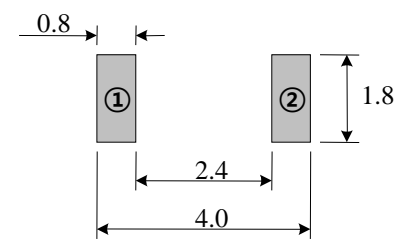
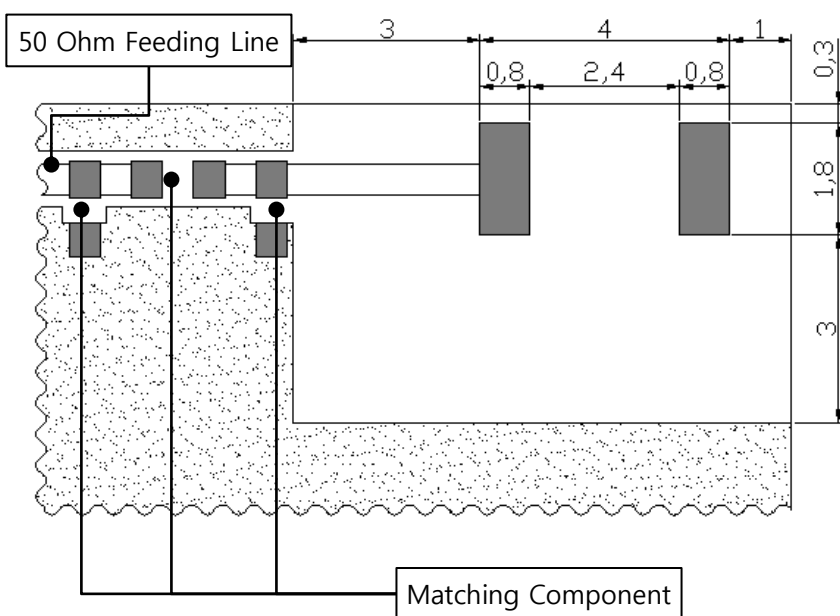
## 2. PCB Design for Test

### 2.1 Evaluation Board Dimension



- ✓ Evaluation board size ~ 10x43
- ✓ Fill Cut Area (GND Clearance) ~ 10x13

### 2.2 PCB Design Guide



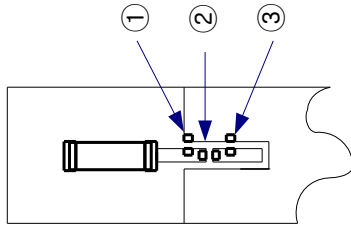
[PCB Solder Land]

No	Pin Assignment
①	Feeding
②	N.C

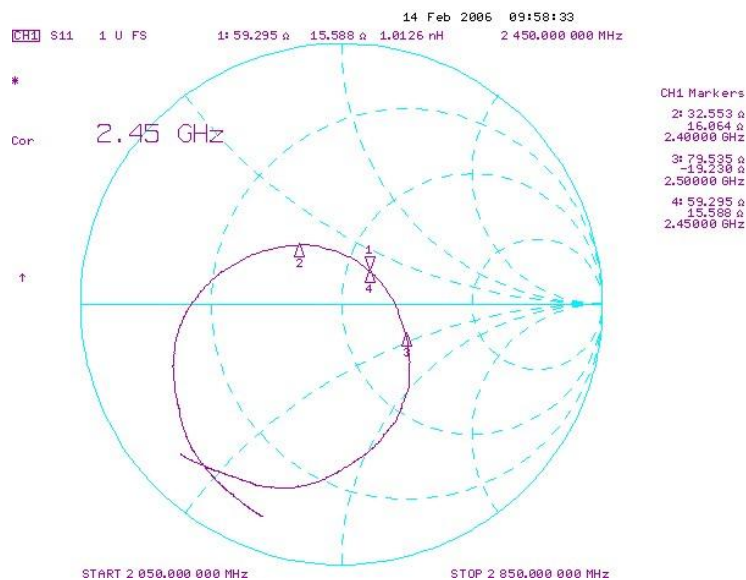
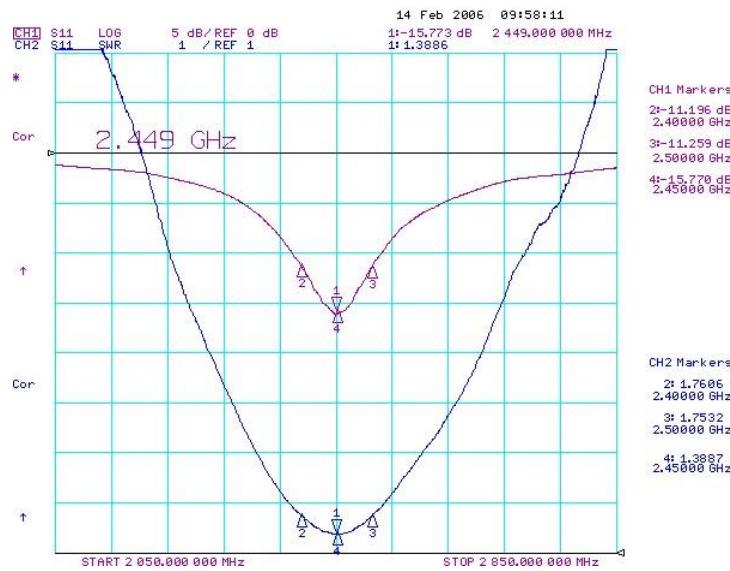
[unit : mm]

### 3. Measurement Result

#### 3.1 Typical Measurement Result (VSWR/RL, Smithchart)



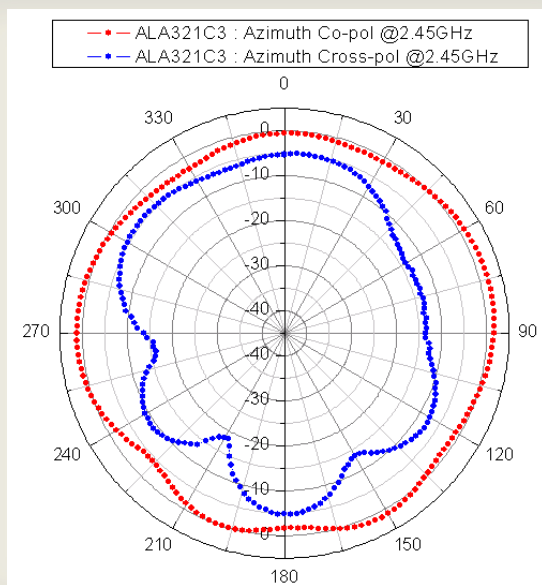
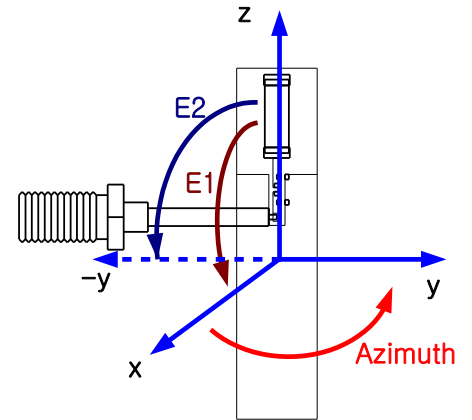
No	Matching Value
①	N.C
②	5.6 nH
③	1.8 nH



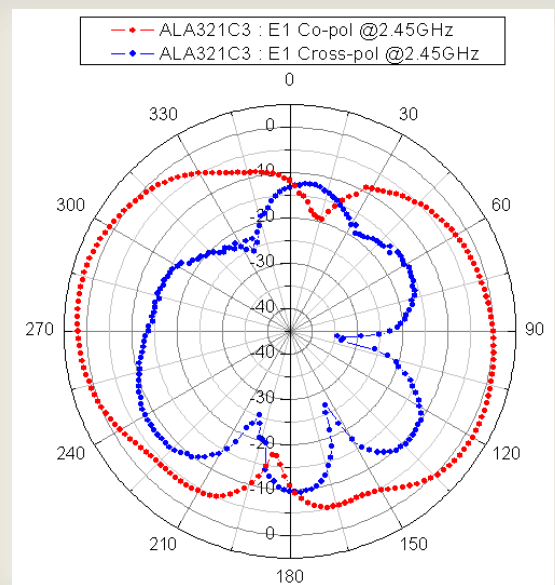
✓ The results are measured on the 10x43mm<sup>2</sup> evaluation board(EVB).

### 3.2 Typical Measurement Result (Gain, Radiation Pattern)

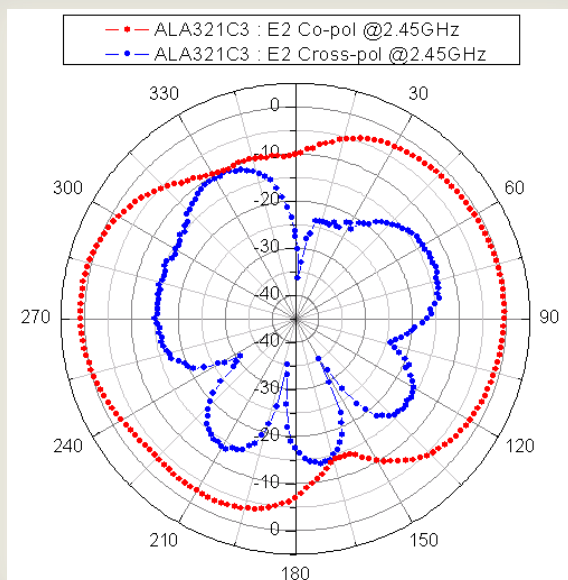
	Peak Gain (dBi)	Avg. Gain (dBi)	Total Avg. Gain (dBi)	Efficiency (%)
Azimuth	2.0	-0.2	-0.6	84
Elevation 1	2.3	-1.8		
Elevation 2	0.9	-2.7		



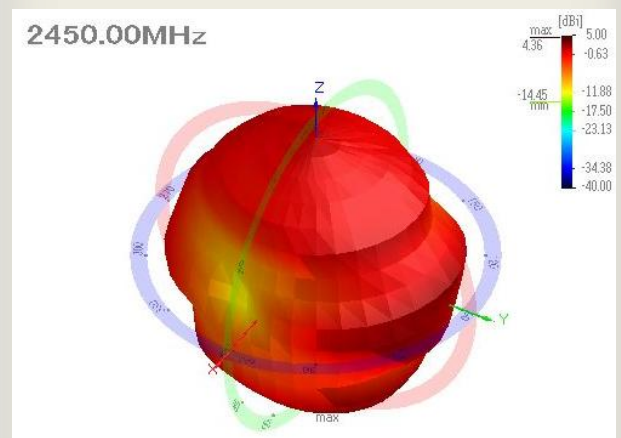
[Azimuth plane @2.45GHz ]



[Elevation1 plane @2.45GHz ]

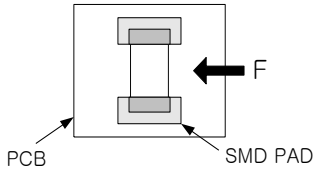


[Elevation2 plane @2.45GHz ]

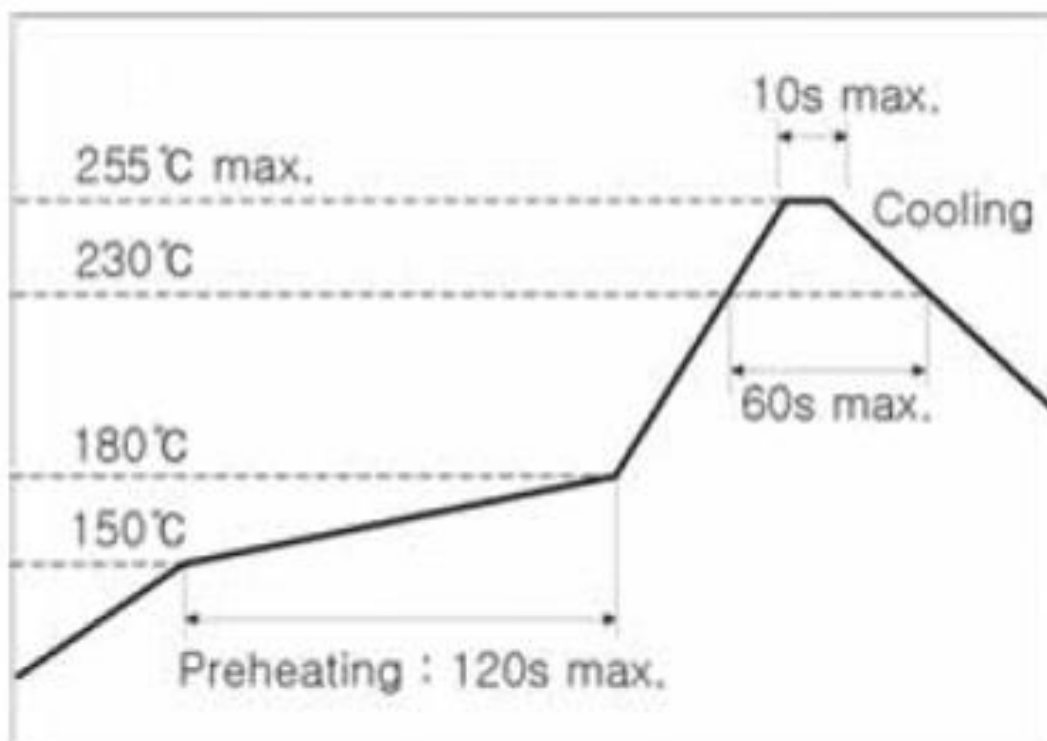


[3D Radiation Pattern]

#### 4. Reliability

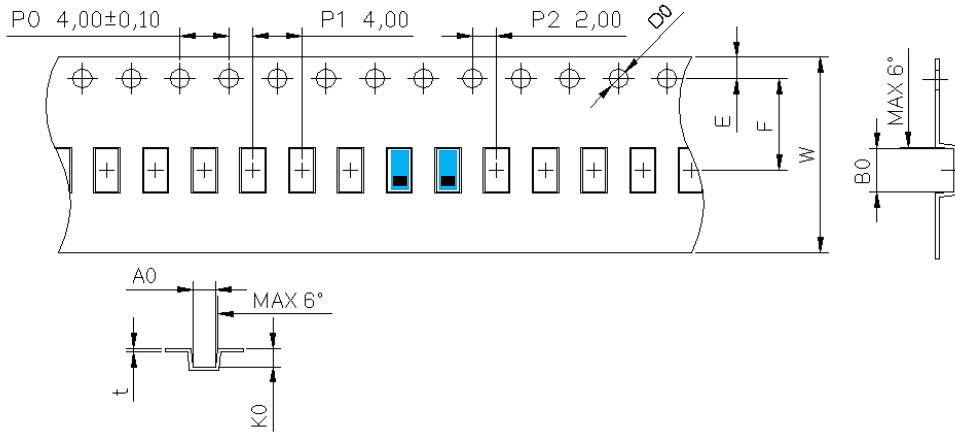
No	Item	Test Condition	Test Requirements
1	Adhesive Strength of Termination	1. Applied force on SMT chip till detached point from PCB. 	1. No mechanical damage by applied force 2. Strength (F) > 3 kgf
2	Thermal Shock (Cycle)	1. Step 1 : $-40 \pm 3^\circ\text{C}$ , 30 min Step 2 : $+125 \pm 3^\circ\text{C}$ , 30 min 2. Number of cycle : 30	1. No visual damage 2. Within electric spec (VSWR)
3	High Temperature Resistance	1. Temperature : $+125 \pm 5^\circ\text{C}$ 2. Time : $1000 \pm 24$ hrs	1. No visual damage 2. Within electric spec (VSWR)
4	Low Temperature Resistance	1. Temperature : $-40 \pm 5^\circ\text{C}$ 2. Time : $1000 \pm 24$ hrs	1. No visual damage 2. Within electric spec (VSWR)
5	Humidity	1. Humidity : 85 % RH Temperature : $+85 \pm 3^\circ\text{C}$ 2. Time : $1000 \pm 24$ hrs	1. No visual damage 2. Within electric spec (VSWR)

#### 5. Soldering Reflow Profile



## 6. Packaging

### 6.1 Carrier Tape Dimension



Item	Spec.	Item	Spec.	Item	Spec.
A0	1.90±0.10	P0	4.00 ±0.10	E	1.75±0.10
B0	3.50±0.10	P1	4.00 ±0.10	F	7.50±0.10
K0	1.50±0.10	P2	2.00 ±0.10	W	16.00±0.30
D0	1.55±0.05	-	-	t	0.30±0.05

### 6.2 Packaging Quantity

Item	Quantity	Dimension
Reel	2,000ea	Φ7" * 12mm
Inner Box	6,000ea (3 reel)	185 * 185 * 68 (mm <sup>3</sup> )
Outer Box1	30,000ea (5 Inner Box)	375 * 200 * 205 (mm <sup>3</sup> )
Outer Box2	60,000ea (10 Inner Box)	390 * 375 * 205 (mm <sup>3</sup> )

### 6.3 Packaging Label

**AMOTECH Co., Ltd.**

5BL-1Lot, 617, Namchon-Dong, Namdong-Gu, Incheon, Korea

**Multilayer Chip Antenna**

P/N : ALA321C3

Lot No :

Quantity : 2,000 pcs    Date : 2010/01/19